



Product / Package Information

Package	QSOP
Body Size	150 mil
Lead Count	16
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.87 E-02	87.7	877000	48.38	483799
Thermosets	Epoxy Resin	Proprietary	2.21 E-03	5.0	50000	2.76	27583
Thermosets	Phenol Resin	Proprietary	2.21 E-03	5.0	50000	2.76	27583
Thermosets	Epoxy Cresol Novolac	29690-82-2	8.83 E-04	2.0	20000	1.10	11033
Other inorganic materials	Carbon Black	1333-86-3	1.32 E-04	0.3	3000	0.17	1655
Subtotal			4.42 E-02	100.0	1000000	55	551653

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.96 E-02	97.5	975000	37.03	370265
Copper & its alloys	Iron	7439-89-6	7.14 E-04	2.35	23500	0.89	8924
Copper & its alloys	Zinc	7440-66-6	3.65 E-05	0.12	1200	0.05	456
Copper & its alloys	Phosphorus	7723-14-0	9.12 E-06	0.03	300	0.01	114
Subtotal			3.04 E-02	100	1000000	38	379759

Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.34 E-03	97.27	972697	2.93	29282
Precious metals	Palladium	7440-05-3	5.45 E-05	2.26	22621	0.07	681
Precious metals	Gold	7440-57-5	1.13 E-05	0.47	4683	0.01	141
Subtotal			2.41 E-03	100.00	1000000	3.01	30104

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.20 E-04	99.99	1000000	0.52	5248

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.34 E-03	100	1000000	2.92	29238

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.49 E-04	77.71	777100	0.31	3107
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	9.95 E-06	3.11	31100	0.01	124
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	9.95 E-06	3.11	31100	0.01	124
Other organic materials	Butyrolactone, gamma-	96-48-0	9.95 E-06	3.11	31100	0.01	124
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	9.95 E-06	3.11	31100	0.01	124
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	9.95 E-06	3.11	31100	0.01	124
Other organic materials	Organosilane	TS ref# 10001	9.95 E-06	3.11	31100	0.01	124
Other inorganic materials	Copper(II) oxide	1317-38-0	9.95 E-06	3.11	31100	0.01	124
Other organic materials	Epoxy resin modifier	TS ref# 10038	1.66 E-06	0.52	5200	0.002	21
Subtotal			3.20 E-04	100.00	1000000	0.40	3998

Package Totals			Weight (g) 8.00 E-02			Percentage (%) 100	PPM 1000000
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ADI Proprietary



Product / Package Information

Package	QSOP
Body Size	150 mils
Lead Count	16
Terminal Finish	100Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.71 E-02	86.20	862000	48.14	481360
Thermosets	Epoxy resin	Proprietary	3.23 E-03	7.50	75000	4.19	41882
Thermosets	Phenol Novolac	9003-35-4	1.72 E-03	4.00	40000	2.23	22337
Other inorganic materials	Antimony Trioxide	1309-64-4	6.46 E-04	1.50	15000	0.84	8376
Thermosets	Brominated Resin	40039-93-8	2.15 E-04	0.50	5000	0.28	2792
Other inorganic materials	Carbon Black	1333-86-4	1.29 E-04	0.30	3000	0.17	1675
Subtotal			4.30 E-02	100	1000000	55.84	558422
Leadframe							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.00 E-02	97.57	975706	39.86	388586
Copper & its alloys	Iron	7439-89-6	7.00 E-04	2.28	22789	0.91	9076
Copper & its alloys	Zinc	7440-66-6	3.88 E-05	0.13	1263	0.05	503
Copper & its alloys	Phosphorus	7723-14-0	7.44 E-06	0.02	242	0.01	97
Subtotal			3.07 E-02	100.00	1000000	39.83	398261
Internal Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.45 E-04	100.0	1000000	0.58	5773
External Leadframe Plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
In & its alloys	In	7440-31-5	8.64 E-04	100.0	1000000	1.12	11204
Bond Wires							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold		4.20 E-04	99.99	1000000	0.54	5448
Chip							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon		1.30 E-03	100.0	1000000	1.68	16823
Die Attach							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.51 E-04	90	800000	0.33	3255
Thermosets	Epoxy Resin	Proprietary	4.70 E-05	15	150000	0.06	610
Others	Curing agent & hardener	Proprietary	1.57 E-05	5	50000	0.02	203
Subtotal			3.14 E-04	100	1000000	0.41	4068
Package Totals			Weight (g)	Percentage (%)		PPM	
			7.71 E-02	100.00		1000000	

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Product / Package Information

Package	QSOP
Body Size	150 mils
Lead Count	16
Terminal Finish	SnPb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.71 E-02	86.20	862000	48.14	481360
Thermosets	Epoxy resin	Proprietary	3.23 E-03	7.50	75000	4.19	41882
Thermosets	Phenol Novolac	9003-35-4	1.72 E-03	4.00	40000	2.23	22337
Other inorganic materials	Antimony Trioxide	1309-64-4	6.46 E-04	1.50	15000	0.84	8376
Thermosets	Brominated Resin	40039-93-8	2.15 E-04	0.50	5000	0.28	2792
Other inorganic materials	Carbon Black	1333-86-4	1.29 E-04	0.30	3000	0.17	1675
Subtotal			4.30 E-02	100	1000000	55.84	558422

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.99 E-02	97.50	975000	38.83	388305
Copper & its alloys	Iron	7439-89-6	7.21 E-04	2.35	23500	0.94	9359
Copper & its alloys	Zinc	7440-66-6	3.68 E-05	0.12	1200	0.05	478
Copper & its alloys	Phosphorus	7723-14-0	9.21 E-06	0.03	300	0.01	119
Subtotal			3.07 E-02	100.00	1000000	39.83	398261

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.45 E-04	100.0	1000000	0.58	5773

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.34 E-04	85.0	850000	0.95	9523
Tin & its alloys	Lead	7439-92-1	1.30 E-04	15.0	150000	0.17	1681
Subtotal			8.64 E-04	100.0	1000000	1.12	11204

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.20 E-04	99.99	1000000	0.54	5448

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.30 E-03	100.0	1000000	1.68	16823

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.51 E-04	80	800000	0.33	3255
Thermosets	Epoxy Resin	Proprietary	4.70 E-05	15	150000	0.06	610
Others	Curing agent & hardener	Proprietary	1.57 E-05	5	50000	0.02	203
Subtotal			3.14 E-04	100	1000000	0.41	4068

Package Totals			Weight (g) 7.71 E-02			Percentage (%) 100.00	PPM 1000000
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